

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.	:	10/559923	Confirmation No. 1496
Applicant	:	Yoshinari Tsukada et al.	
Filed	:	December 8, 2005	
TC/A.U.	:	2826	
Examiner	:	Alexander O. Williams	
Title	:	SEMICONDUCTOR DEVICE REDUCING WARPING DUE TO HEAT PRODUCTION (as amended)	
Docket No.	:	SHM-16366	
Customer No.	:	040854	

AMENDMENT "B"

(In response to Paper No./Mail Date 20080105)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This amendment is filed in response to the Office action dated January 11, 2008. The three month period for responding to the Office action expires on April 11, 2008. Please amend the above-identified application as follows:

- **Amendments to the Specification** begin on page 2 of this paper.
- **Amendments to the Claims** are reflected in the listing of claims, which begins on page 3 of this paper.
- **Remarks/Arguments** begin on page 8 of this paper.